

IGBT - Power, Co-PAK N-Channel, Field Stop VII (FS7), Non SCR, Power TO247-3L, 1200 V, 1.7 V, 75 A

FGY75T120SWD

Description

Using the novel field stop 7th generation IGBT technology and the Gen7 Diode in TO247 3–lead package, FGY75T120SWD offers the optimum performance with low switching and conduction losses for high–efficiency operations in various applications like Solar, UPS and ESS.

Features

- Maximum Junction Temperature $T_J = 175$ °C
- Positive Temperature Coefficient for Easy Parallel Operation
- High Current Capability
- Smooth and Optimized Switching
- Low Switching Loss
- RoHS Compliant

Applications

- Boost and Inverter in Solar System
- UPS
- Energy Storage System

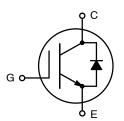
MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

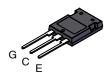
Parameter	Symbol	Value	Unit	
Collector-to-Emitter Voltage		V _{CES}	1200	V
Gate-to-Emitter Voltage		V_{GES}	±20	
Transient Gate-to-Emitter	· Voltage		±30	
Collector Current	T _C = 25°C	I _C	150	
	T _C = 100°C		75	Α
Power Dissipation	T _C = 25°C	P_{D}	714	W
	T _C = 100°C		357	
Pulsed Collector Current	T _C = 25°C, t _p = 10 μs (Note 1)	I _{CM}	300	Α
Diode Forward	T _C = 25°C	lF	150	
Current	T _C = 100°C		75	
Pulsed Diode Maximum Forward Current	$T_{C} = 25^{\circ}C,$ $t_{p} = 10 \ \mu s$ (Note 1)	I _{FM}	300	
Operating Junction and St Temperature Range	T _J , T _{STG}	-55 to 175	°C	
Lead Temperature for Solo	TL	260		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

BV _{CES}	V _{CE(SAT)}	I _C
1200 V	1.7 V	75.0 A

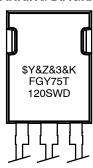
PIN CONNECTIONS





TO247-3LD CASE 340CD

MARKING DIAGRAM



\$Y = onsemi Logo &Z = Assembly Plant Code &3 = 3-Digit Date Code &K = 2-Digit Lot Traceability Code FGY75T120SWD = Specific Device code

ORDERING INFORMATION

Device	Package	Shipping
FGY75T120SWD	TO247-3LD (Pb-Free)	30 Units / Tube

^{1.} Repetitive rating: pulse width limited by max. Junction temperature.

THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case for IGBT	$R_{ heta JC}$	0.21	°C/W
Thermal Resistance, Junction-to-Case for Diode		0.35	
Thermal Resistance, Junction-to-Ambient	$R_{ heta JA}$	40	

ELECTRICAL CHARACTERISTICS OF THE IGBT ($T_J = 25$ °C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector-to-Emitter Breakdown Voltage	BV _{CES}	$V_{GE} = 0 \text{ V, I}_{C} = 5 \text{ mA}$	1200	_	_	V
Breakdown Voltage Temperature Coefficient	$\Delta BV_{CES} / \Delta T_{J}$	V _{GE} = 0 V, I _C = 5 mA	-	1223	-	mV/°C
Collector-to-Emitter Cut-Off Current	I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	-	_	40	μΑ
Gate-to-Emitter Leakage Current	I _{GES}	V _{GE} = 20 V, V _{CE} = 0 V	-	-	±400	nA
ON CHARACTERISTICS						
Gate-to-Emitter Threshold Voltage	V _{GE(TH)}	$V_{GE} = V_{CE}$, $I_C = 75 \text{ mA}$	5.6	6.55	7.4	V
Collector-to-Emitter Saturation	V _{CE(SAT)}	V _{GE} = 15 V, I _C = 75 A, T _J = 25°C	1.35	1.68	2.0	V
Voltage		V _{GE} = 15 V, I _C = 75 A, T _J = 175°C	_	2.24	-	
DYNAMIC CHARACTERISTICS	-			-	-	-
Input Capacitance	C _{IES}	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	-	6331	_	pF
Output Capacitance	C _{OES}		-	234	-	
Reverse Transfer Capacitance	C _{RES}		-	29.6	-	
Total Gate Charge	Q_{G}	V _{CE} = 600 V, V _{GE} = 15 V, I _C = 75 A	-	214	-	nC
Gate-to-Emitter Charge	Q_{GE}		-	53.9	-	1
Gate-to-Collector Charge	Q_{GC}		-	77.7	-	
SWITCHING CHARACTERISTIC, II	NDUCTIVE LOAI	D				
Turn-On Delay Time	t _{d(on)}	V _{CE} = 600 V, V _{GE} = 15 V,	-	42	-	ns
Turn-Off Delay Time	t _{d(off)}	I_C = 37.5 A, R_G = 4.7 Ω, T_J = 25°C	-	221	-	
Rise Time	t _r]	-	27	-	
Fall Time	t _f]	-	77	-	
Turn-On Switching Loss	E _{on}]	-	2.12	-	mJ
Turn-Off Switching Loss	E _{off}] [-	1.43	-	
Total Switching Loss	E _{ts}		-	3.55	-	
Turn-On Delay Time	t _{d(on)}	V _{CE} = 600 V, V _{GE} = 15 V,	-	42	-	ns
Turn-Off Delay Time	t _{d(off)}	I_C = 75 A, R_G = 4.7 Ω, T_J = 25°C	-	171	-	
Rise Time	t _r		-	56	-	
Fall Time	t _f]	-	66	-	
Turn-On Switching Loss	E _{on}		_	5.00	-	mJ
Turn-Off Switching Loss	E _{off}		_	2.32	-	
Total Switching Loss	E _{ts}	1	-	7.32	-	1

ELECTRICAL CHARACTERISTICS OF THE IGBT ($T_J = 25$ °C unless otherwise noted) (continued)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
SWITCHING CHARACTERISTIC, IN	IDUCTIVE LOAD)				•
Turn-On Delay Time	t _{d(on)}	V _{CE} = 600 V, V _{GE} = 15 V,	_	38	_	ns
Turn-Off Delay Time	t _{d(off)}	I_C = 37.5 A, R_G = 4.7 Ω, T_J = 175°C	_	276	-	
Rise Time	t _r	-	_	26	-	1
Fall Time	t _f		_	132	-	
Turn-On Switching Loss	E _{on}		_	3.50	-	mJ
Turn-Off Switching Loss	E _{off}		_	2.31	-	1
Total Switching Loss	E _{ts}		_	5.81	-	1
Turn-On Delay Time	t _{d(on)}	$V_{CE} = 600 \text{ V}, V_{GE} = 15 \text{ V},$	-	38	-	ns
Turn-Off Delay Time	t _{d(off)}	I_C = 75 A, R_G = 4.7 Ω, T_J = 175°C	_	210	-	1
Rise Time	t _r		_	53	-	1
Fall Time	t _f		_	115	-	1
Turn-On Switching Loss	E _{on}		_	7.29	-	mJ
Turn-Off Switching Loss	E _{off}		_	3.50	-	1
Total Switching Loss	E _{ts}		_	10.79	-	1
DIODE CHARACTERISTIC						
Diode Forward Voltage	V_{F}	I _F = 75 A, T _J = 25°C	1.62	1.84	2.22	V
		I _F = 75 A, T _J = 175°C	-	1.91	-	
DIODE SWITCHING CHARACTERIS	STIC, INDUCTIV	E LOAD				
Reverse Recovery Time	t _{rr}	$V_R = 600 \text{ V}, I_F = 37.5 \text{ A}, \\ dI_F/dt = 1000 \text{ A/}\mu\text{s}, \\ T_J = 25^{\circ}\text{C}$	_	136	_	ns
Reverse Recovery Charge	Q _{rr}		_	2340	-	nC
Reverse Recovery Energy	E _{rec}		_	0.7	-	mJ
Peak Reverse Recovery Current	I _{RRM}		_	34.5	-	Α
Reverse Recovery Time	t _{rr}	V _R = 600 V, I _F = 75 A,	_	204	-	ns
Reverse Recovery Charge	Q _{rr}	dl _F /dt = 1000 A/μs, Τ _J = 25°C	_	3974	-	nC
Reverse Recovery Energy	E _{rec}	· ·	_	1.3	-	mJ
Peak Reverse Recovery Current	I _{RRM}		_	38.8	-	Α
Reverse Recovery Time	t _{rr}	$V_R = 600 \text{ V}, I_F = 37.5 \text{ A},$	-	236	-	ns
Reverse Recovery Charge	Q _{rr}	$dI_F/dt = 1000 \text{ A/}\mu\text{s},$ $T_J = 175^{\circ}\text{C}$	-	5980	-	nC
Reverse Recovery Energy	E _{rec}		_	2.1	-	mJ
Peak Reverse Recovery Current	I _{RRM}		_	50.7	-	Α
Reverse Recovery Time	t _{rr}	$V_R = 600 \text{ V}, I_F = 75 \text{ A},$	_	334	-	ns
Reverse Recovery Charge	Q _{rr}	dI _F /dt = 1000 A/μs, T _J = 175°C	_	9544	_	nC
Reverse Recovery Energy	E _{rec}		_	3.5	_	mJ
Peak Reverse Recovery Current	I _{RRM}		_	57.1	-	Α

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

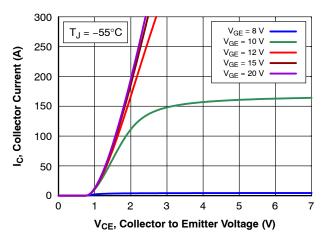


Figure 1. Output Characteristics

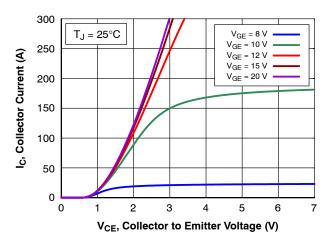


Figure 2. Output Characteristics

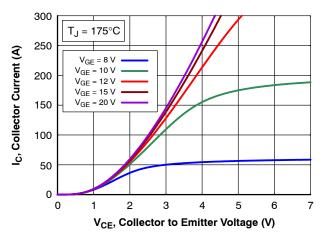


Figure 3. Output Characteristics

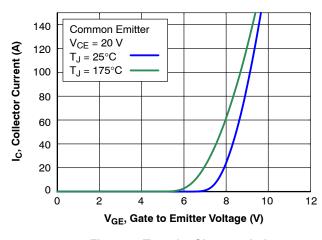


Figure 4. Transfer Characteristics

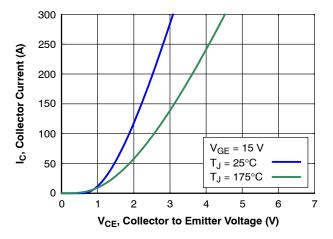


Figure 5. Saturation Voltage Characteristics

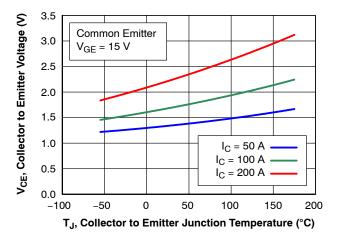


Figure 6. Saturation Voltage vs Junction Temperature

TYPICAL CHARACTERISTICS (CONTINUED)

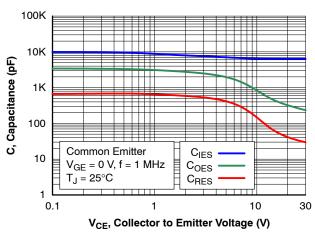


Figure 7. Capacitance Characteristics

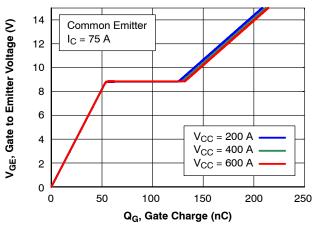


Figure 8. Gate Charge Characteristics

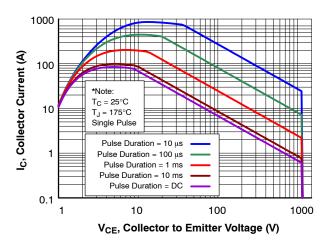


Figure 9. SOA Characteristics

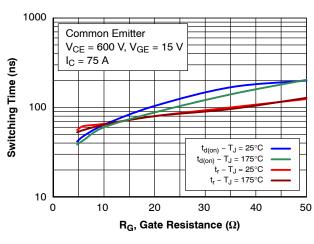


Figure 10. Turn-On Time vs Gate Resistance

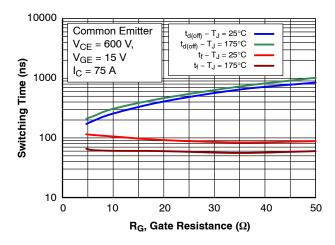


Figure 11. Turn-Off Time vs Gate Resistance

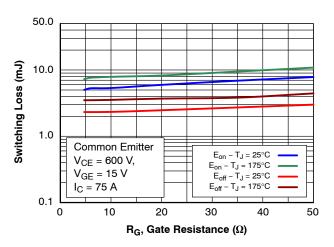


Figure 12. Switching Loss vs Gate Resistance

TYPICAL CHARACTERISTICS (CONTINUED)

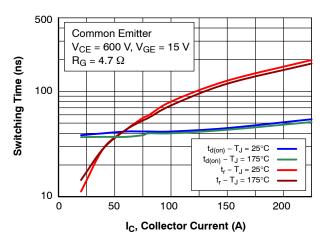


Figure 13. Turn-On Time vs Collector Current

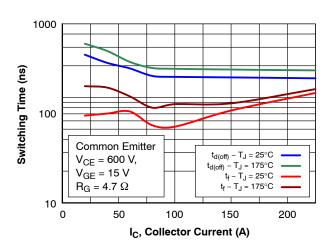


Figure 14. Turn-Off Time vs Collector Current

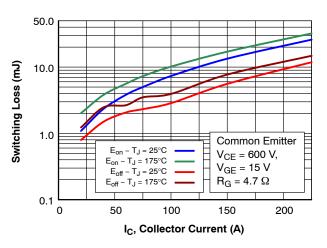


Figure 15. Switching Loss vs Collector Current

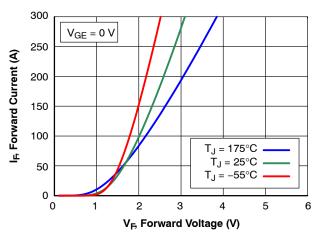


Figure 16. Diode Forward Characteristics

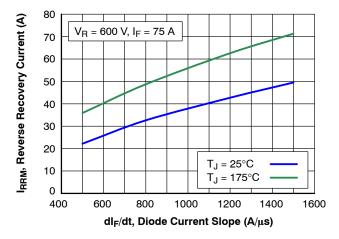


Figure 17. Diode Reverse Recovery Current

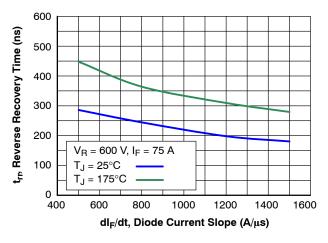


Figure 18. Diode Reverse Recovery Time

TYPICAL CHARACTERISTICS (CONTINUED)

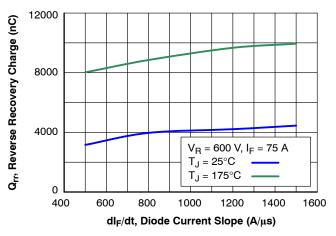


Figure 19. Diode Stored Charge Characteristics

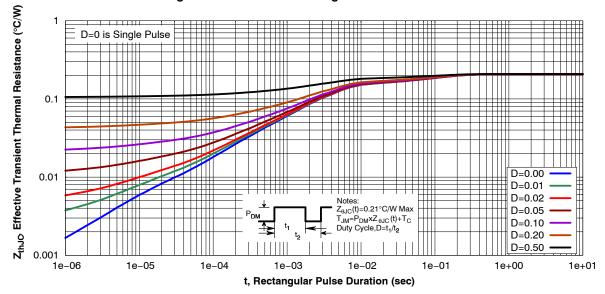


Figure 20. Transient Thermal Impedance of IGBT

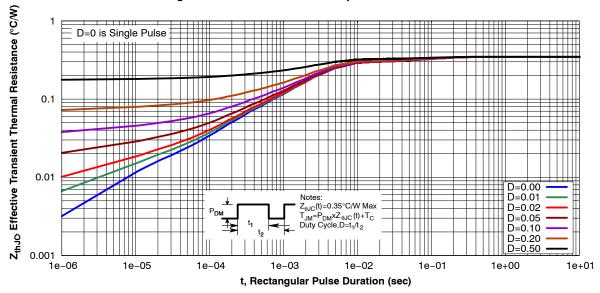


Figure 21. Transient Thermal Impedance of Diode

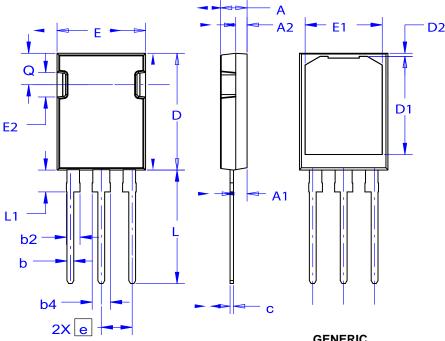


TO-247-3LD CASE 340CD ISSUE A

DATE 18 SEP 2018

NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY STANDARDS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- D. DIMENSION AND TOLERANCE AS PER ASME Y14.5-2009.



DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A 1	2.20	2.40	2.60		
A2	1.80	2.00	2.20		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.12	4.32	4.52		
е	~	5.45	~		
L	19.90	20.00	20.10		
L1	3.69	3.81	3.93		
Q	5.34	5.46	5.58		
b	1.10	1.20	1.30		
b2	2.10	2.24	2.39		
b4	2.87	3.04	3.20		
С	0.51	0.61	0.71		
D1	16.63	16.83	17.03		
D2	0.51	0.93	1.35		
E1	13.40	13.60	13.80		

GENERIC
MARKING DIAGRAM*

XXXXXXXX AYWWG

XXXX = Specific Device Code A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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AFGY160T65SPD-B4 IGW30N60TP IGW40N60TP IGW50N60TP IHW30N65R5 IKFW40N60DH3E IKP15N65H5 IKQ100N60T

IKQ120N60T IKW30N65WR5 IKW75N60H3 IKZ50N65NH5 IKZ75N65NH5 FGD3040G2-F085C FGH4L50T65SQD FGHL40T65MQDT

FGHL50T65MQD FGHL50T65MQDTL4 FGHL75T65LQDT FGHL75T65MQD FGHL75T65MQDT FGHL75T65MQDTL4

FGY75T120SWD EL3120S1(TA)(SAS)-V IHW15N120E1 IKQ75N120CS6 IKA08N65ET6 IKW50N65WR5 SL15T65FK

KGF50N65KDF-U/H IHFW40N65R5S IKQ75N120CH3 IHW30N160R5 SGM100HF12A1TFD CRG50T60AK3SD CRG40T60AN3S